

Product Change Notification - GBNG-14WQIZ459

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Date:

20 Aug 2018

Product Category:

8-bit Microcontrollers; Capacitive Touch Sensors

Affected CPNs:**Notification subject:**

CCB 3370.001 Initial Notice: Qualification of MMT as a new assembly site in selected Atmel products of 19.6K, 35.4K and 35.5K wafer technologies available in 32L VQFN package using palladium coated copper wire with gold flash (CuPdAu) bond wire.

Notification text:**PCN Status:**

Initial notification.

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:

Qualification of MMT as a new assembly site in selected Atmel products of 19.6K, 35.4K and 35.5K wafer technologies available in 32L VQFN package using palladium coated copper wire with gold flash (CuPdAu) bond wire.

Pre Change:

Assembled at ANAC assembly site with punched as a singulation method, using palladium coated copper wire (PdCu) bond wire.

Post Change:

Assembled at MMT assembly site with sawn as a singulation method, using palladium coated copper wire with gold flash (CuPdAu) bond wire

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	Amkor Assembly & Test (Shanghai) Co., LTD (ANAC)	Microchip Technology Thailand (Branch)(MMT)
Wire material	PdCu	CuPdAu
Die attach material	8290	3280
Molding compound material	G700	G700
Lead frame material	C194	C194
Singulation method	Punched	Sawn

Impacts to Data Sheet:

Yes

Change Impact:

None

Reason for Change:

To improve on-time delivery performance by qualifying MMT as a new assembly site.

Change Implementation Status:

In Progress

Estimated Qualification Completion Date:

August 2018

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	August 2018				
Workweek	31	32	33	34	35
Initial PCN Issue Date				X	
Qual Report Availability					X

Final PCN Issue Date					X
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Method to Identify Change:

Traceability code

Qualification Plan:

Please open the attachments included with this PCN labeled as PCN_#_Qual Plan.

Revision History:

August 20, 2018: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

[PCN_GBNG-14WQIZ459_Qual Pan.pdf](#)

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